



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BSC0911ND	<b>Issued</b>	03. May 2021
<b>MA#</b>	MA001013774		
<b>Package</b>	PG-TISON-8-3	<b>Weight*</b>	101.91 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	0.285	0.28	0.28	2792	2792
chip_2	inorganic material	silicon	7440-21-3	0.848	0.83	0.83	8324	8324
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		101	
	non noble metal	zinc	7440-66-6	0.041	0.04		403	
	non noble metal	iron	7439-89-6	0.822	0.81		8062	
	non noble metal	copper	7440-50-8	33.360	32.73	33.59	327347	335913
wire	noble metal	gold	7440-57-5	0.069	0.07	0.07	672	672
encapsulation	organic material	carbon black	1333-86-4	0.092	0.09		898	
	plastics	epoxy resin	-	4.715	4.63		46269	
	inorganic material	silicondioxide	60676-86-0	40.973	40.20	44.92	402048	449215
leadfinish	non noble metal	tin	7440-31-5	1.108	1.09	1.09	10872	10872
plating	noble metal	silver	7440-22-4	0.186	0.18	0.18	1823	1823
solder	non noble metal	tin	7440-31-5	0.034	0.03		338	
	noble metal	silver	7440-22-4	0.043	0.04		423	
	non noble metal	lead	7439-92-1	1.646	1.62	1.69	16155	16916
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.01		52	
	non noble metal	zinc	7440-66-6	0.021	0.02		208	
	non noble metal	iron	7439-89-6	0.424	0.42		4163	
	non noble metal	copper	7440-50-8	17.228	16.90	17.35	169050	173473
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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